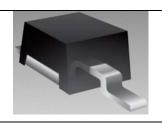
MATERIAL DECLARATION SHEET



Material Number	CD216A-B SERIES					
Product Line	Semiconductor Products					
Compliance Date	2004/8/2					
RoHS Compliant	Yea	MSL	1			



No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Dice	Silica compound	2.2	Silicon	7440-21-3	98%	13.31%	13.58%
				Nickel	7440-02-0	2%	0.27%	
2	Solder Paste	High-melting point solder	0.81	Lead*	7439-92-1	92.5%	4.63%	5.00%
				Tin	7440-31-5	5.0%	0.25%	
				Silver	7440-22-4	2.5%	0.12%	
	Lead frame &clip	Copper Alloy	5.27	Copper	7440-50-8	99.950%	32.48%	32.53%
3				Iron	7439-89-6	0.1%	0.04%	
				Phosphorus	7723-14-0	0.034%	0.01%	
4	Epoxy material	Green molding compound	7.78	Silica, amorphous, fused	60676-86-0	83%	39.86%	48.02%
				Epoxy resin	29690-82-2	13.5%	6.48%	
				BTDA	2421-28-5	0.55%	0.26%	
				Silica, quartz	14808-60-7	2.4%	1.16%	
				Carbon black	1333-86-4	0.55%	0.26%	
5	Plating cover	Sn plating cover	0.14	Tin	7440-31-5	100%	0.87%	0.87%
	1	Total weight	16.2				1	

MATERIAL DECLARATION SHEET



This Document was updated on: 2015-4-27

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.

2. * 7(a)-Lead in high melting temperature type solders (i.e. lead- based alloys containing 85% by weight or more lead)